

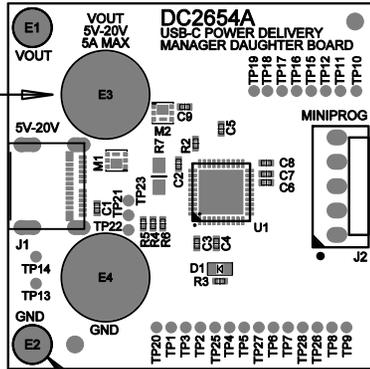
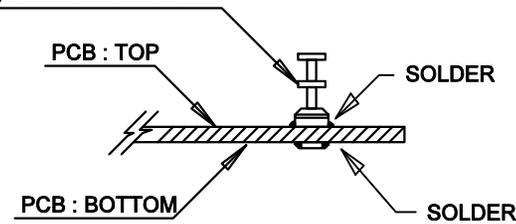
REVISION HISTORY

ECO	REV	DESCRIPTION	APPR	DATE
-	03	PRODUCTION	ZP	05-31-19

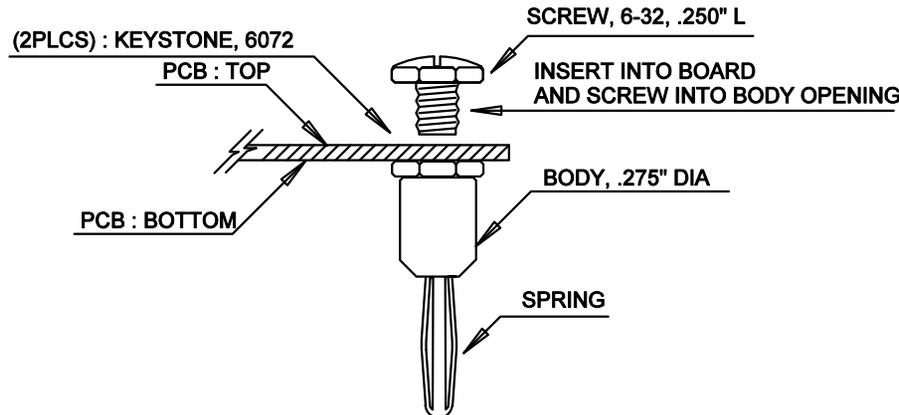
NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELCIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
5. APPLY ASSEMBLY STAMP OR QA STAMP TO BOTTOM OF BOARD (UNSHOWY AREA).
6. INSTALL TURRETS AS SHOWN BELOW:

(2PLCS) : MILL-MAX 2308



7. INSTALL INTERNAL THREAD BANANA PLUG AS SHOWN BELOW:
 - TIN PLATE LUG IS NOT USED, CAN BE DISCARDED.
 - SCREW IS INSERTED AS SHOWN.



8. APPLY DEMO S/N AT AREA ON BOTTOM SIDE AS SHOWN ON SHEET 2.

APPROVALS		 		1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 WWW.ANALOG.COM
PCB DES.	NC	TITLE: TOP ASSEMBLY DRAWING: USB-C POWER DELIVERY MANAGER DAUGHTER BOARD		
APP ENG.	ZP			
SIZE	IC NO.	LTC4162	REV.	
N/A		DEMO CIRCUIT 2654A	03	
SCALE = NONE			SHT 1 of 2	